

|   |   |  |                   |
|---|---|--|-------------------|
| <b>PCN Number:</b>                        | 20221215006.1   | <b>PCN Date:</b>                       | December 16, 2022 |
| <b>Title:</b>                             | Qualification of ATJ as Additional Chip on Chip process site for Select Package Devices |  |                   |
| <b>Customer Contact:</b>                  | <a href="#">PCN Manager</a>   | <b>Dept:</b>                           | Quality Services  |
| <b>Proposed 1<sup>st</sup> Ship Date:</b> | Mar 16, 2023  | <b>Sample requests accepted until:</b> | Jan 16, 2023*     |

\*Sample requests received after (Jan 16, 2023) will not be supported.

|                                     |                           |                          |                     |
|-------------------------------------|---------------------------|--------------------------|---------------------|
| <b>Change Type:</b>                 |                           |                          |                     |
| <input checked="" type="checkbox"/> | Assembly Site             | <input type="checkbox"/> | Design              |
| <input checked="" type="checkbox"/> | Assembly Process          | <input type="checkbox"/> | Data Sheet          |
| <input checked="" type="checkbox"/> | Assembly Materials        | <input type="checkbox"/> | Part number change  |
| <input type="checkbox"/>            | Mechanical Specification  | <input type="checkbox"/> | Test Site           |
| <input checked="" type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process        |
|                                     |                           | <input type="checkbox"/> | Wafer Bump Site     |
|                                     |                           | <input type="checkbox"/> | Wafer Bump Material |
|                                     |                           | <input type="checkbox"/> | Wafer Bump Process  |
|                                     |                           | <input type="checkbox"/> | Wafer Fab Site      |
|                                     |                           | <input type="checkbox"/> | Wafer Fab Materials |
|                                     |                           | <input type="checkbox"/> | Wafer Fab Process   |

### PCN Details

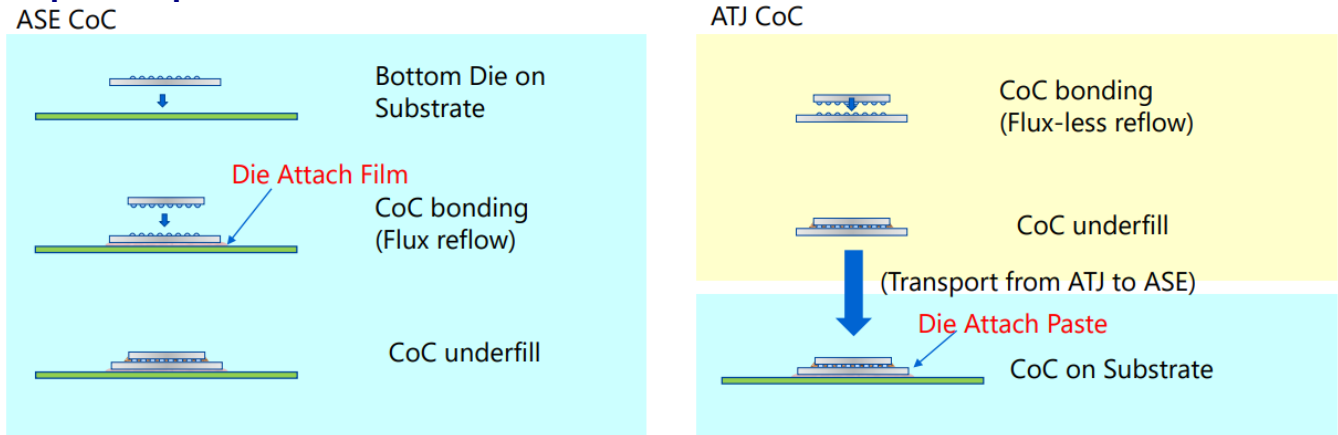
#### Description of Change:

Texas Instruments Incorporated is announcing the qualification ATJ as Additional Chip on Chip (CoC) process Site for select device listed in the "Product Affected" Section. Current Chip on Chip sites and Material differences are as follows.

#### Material Differences:



|                | <b>ASE</b>      | <b>ATJ</b>       |
|----------------|-----------------|------------------|
| Mount Compound | Die attach film | Die attach paste |

#### Chip on Chip Method:



#### Sample Package Marking Differences:

| Device      | <b>ASE CoC</b> | <b>ATJ Coc</b> |
|-------------|----------------|----------------|
| DLPC7541ZDC |                |                |

|             |  |  |  |  |
|-------------|--|--|--|--|
| DLPC7540ZDC |  |  <p>DLPC7540ZDC<br/>T6WX5XBG-0002W6<br/>TAIWAN WWYYHAF<br/>Lot Code <span style="float: right;">G1</span></p> |  <p>DLPC7540ZDC<br/>T6WX5XBG-0002W6<br/>TAIWAN WWYYHBF<br/>Lot Code <span style="float: right;">G1</span></p> |  |
|-------------|--|--|--|--|

**Reason for Change:**

Continuity of supply.

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

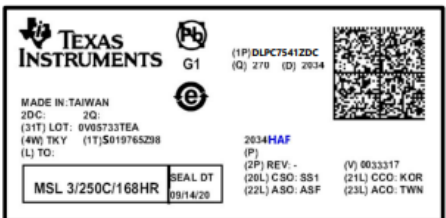
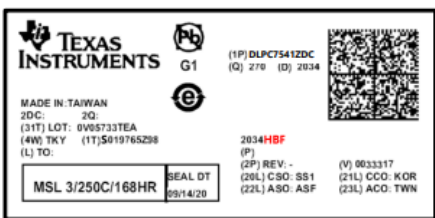
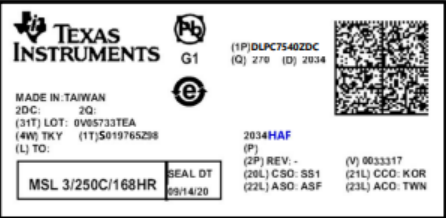
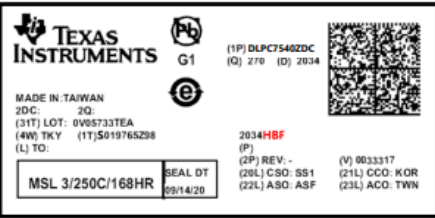
None

**Impact on Environmental Ratings:**

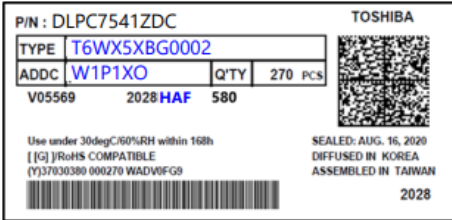
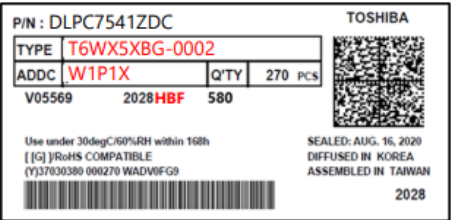
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

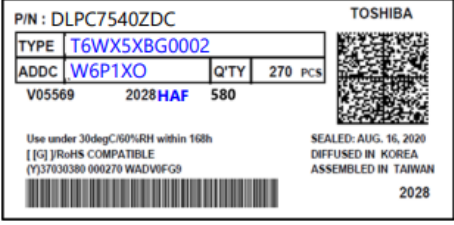
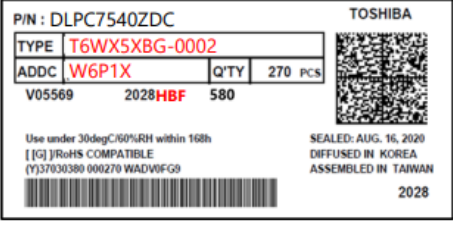
|   |   |   |   |
|---|---|---|---|
| <b>RoHS</b>                                   | <b>REACH</b>                                  | <b>Green Status</b>                           | <b>IEC 62474</b>                              |
| <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change |

**Changes to product identification resulting from this PCN:**

| Device      | ASE CoC   | ATJ Coc  |
|-------------|---|--|
| DLPC7541ZDC |  |  |
| DLPC7540ZDC |  |  |

**Sample TSB shipping label**

| Device      | ASE CoC   | ATJ Coc  |
|-------------|---|--|
| DLPC7541ZDC |  |  |

|             |   |  |
|-------------|---|--|
| DLPC7540ZDC |  |  |
|             | <b>Product Affected:</b>  |  |
| DLPC6540ZDC | DLPC7540ZDC   | DLPC7541ZDC  |

## Qualification Report

Approve Date 28-Jul-2022

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Items                      | Reference   | Test Condition  | Criteria   | Test time/cycle | Sample size  | Result |
|----------------------------|-------------|---|------------|-----------------|--------------|--------|
| Preconditioning            | JESD22-A113 | Bake : 125degCx24H<br>Moisture absorption : 30degC60%RHx216H<br>Reflow : 250degCMax, 3Times | No failure | -               | 77pcs x 3LOT | Pass   |
| TC<br>(Thermal Cycle Test) | JESD22-A104 | -55degC ~ 125degC<br>with Preconditioning   | No failure | 700cyc          | 25pcs x 3LOT | Pass   |
| uHAST<br>(Unbiased HAST)   | JESD22-A118 | 110degC/85%RH<br>with Preconditioning   | No failure | 264h            | 25pcs x 3LOT | Pass   |

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location    | E-Mail   |
|-------------|--|
| WW PCN Team | <a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a> |

### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disdaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on [ti.com](http://ti.com) or provided in conjunction with such TI products. TI's provision of

these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.